

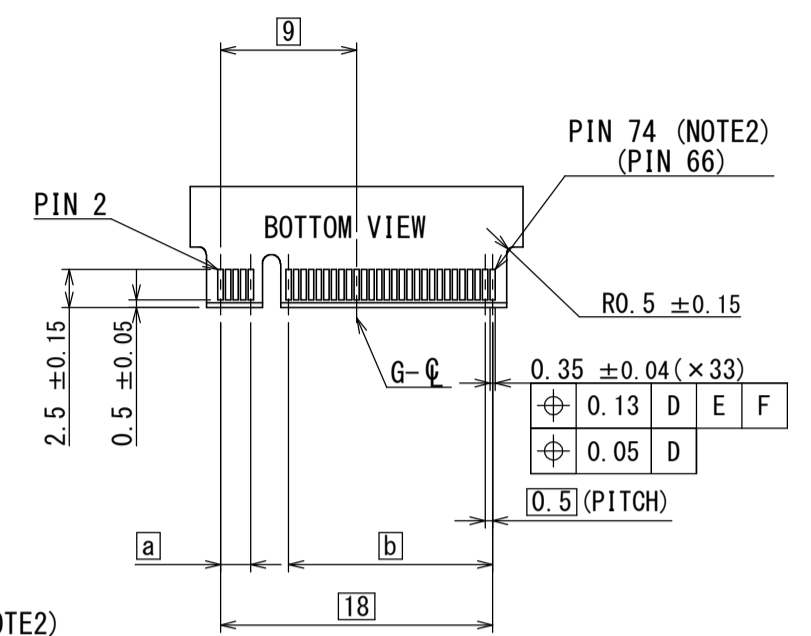
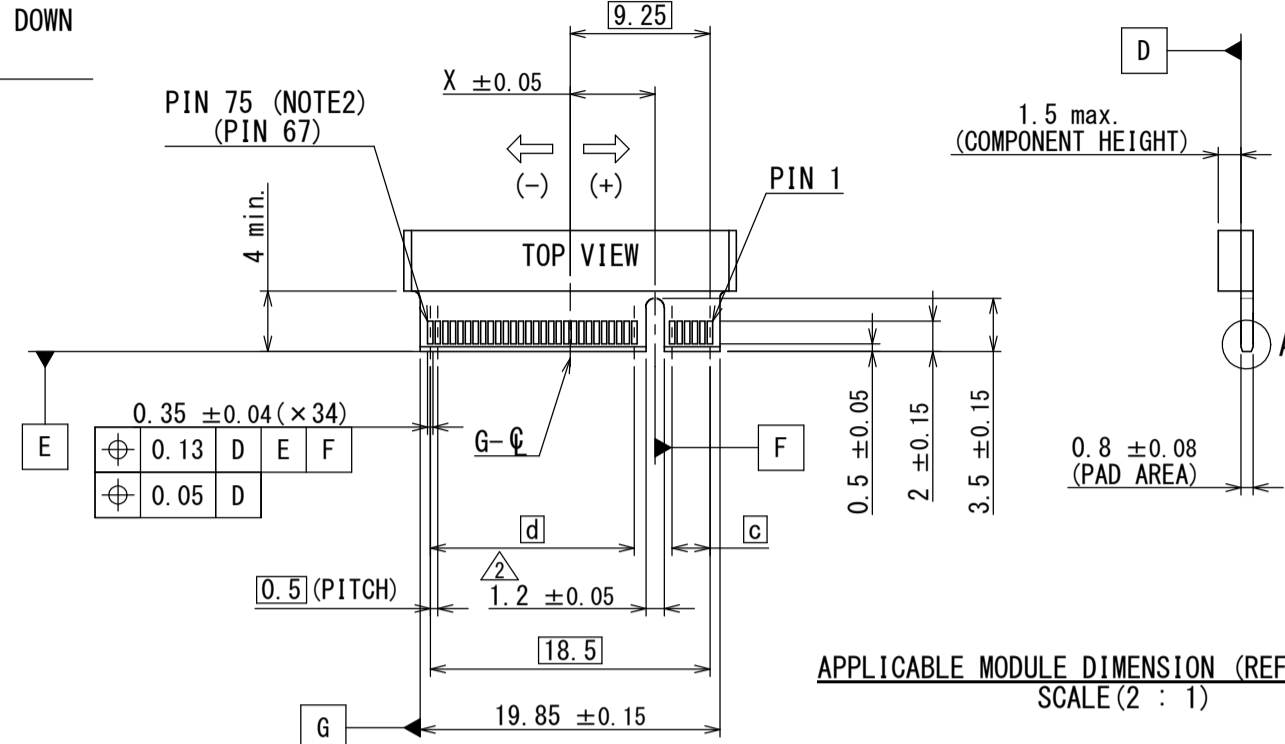
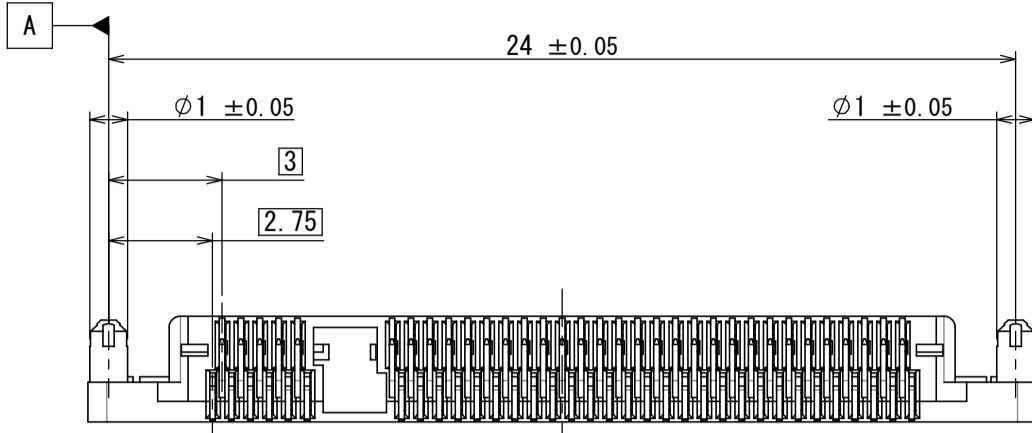
DESIGNATION

SM3ZS067B120\*\*2

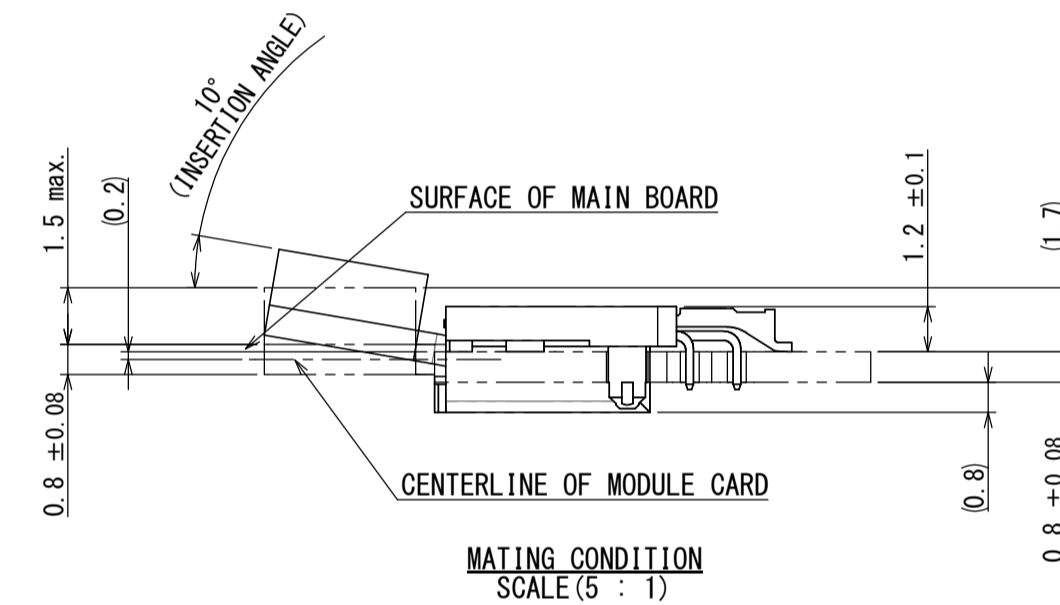
SERIES  
シリーズ  
Z: LIF TYPE  
Z: 低挿入タイプ  
S: STANDARD  
R: REVERSE  
NO. OF CONTACTS  
芯数  
MOUNTING TYPE  
実装タイプ  
B: MID MOUNT TYPE

MODIFICATION CODE  
モディファイコード  
1: THROUGH HOLE HOLD DOWN  
2: SMT HOLD DOWN  
KEY POSITION  
△  
TYPE: B, E, M  
CONTACT FINISH  
接点仕上げ  
A: Au (0.13 μm MIN)  
B: Au (0.25 μm MIN)  
PRODUCT HEIGHT  
製品高さ  
120: 1.2mm

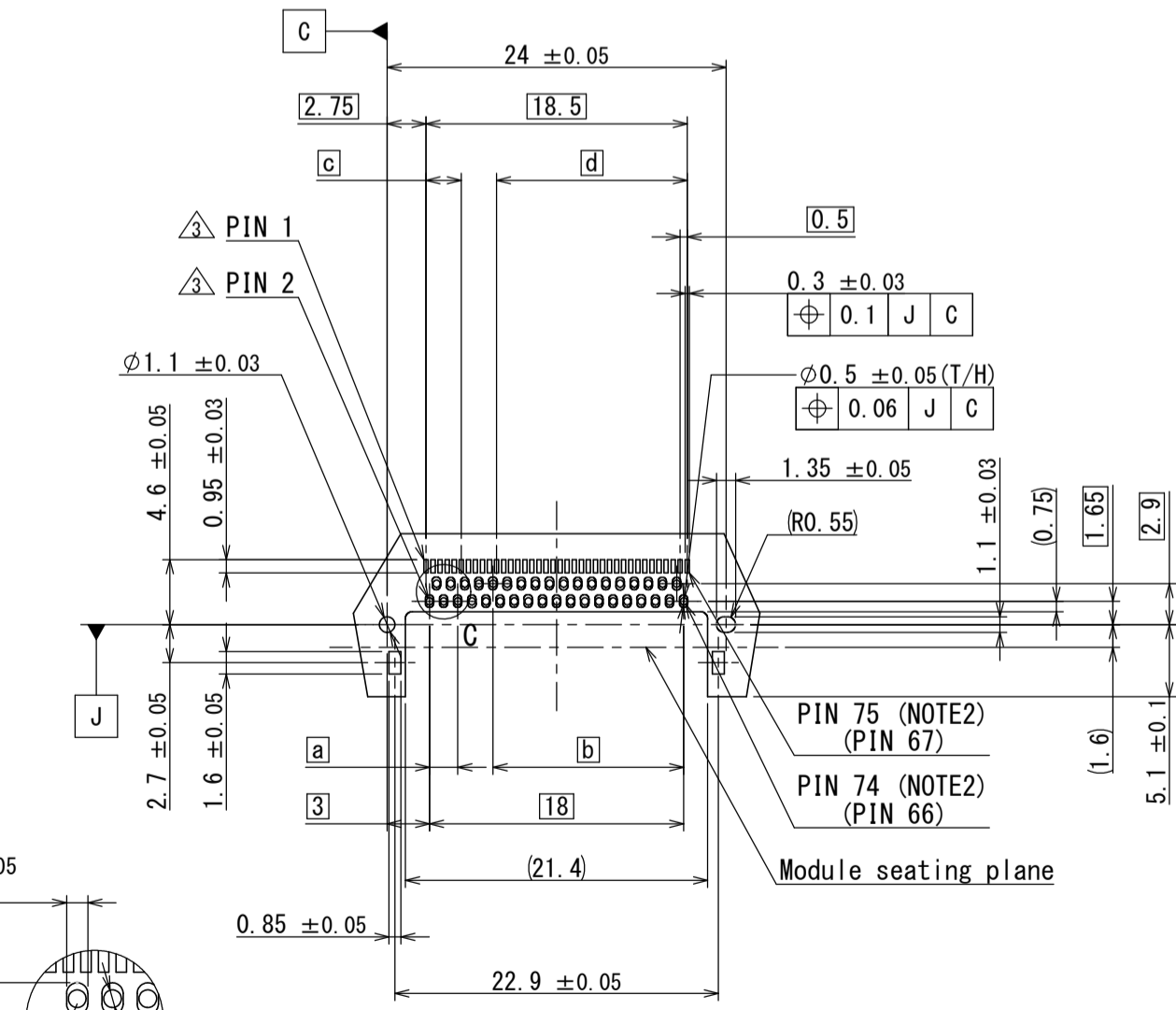
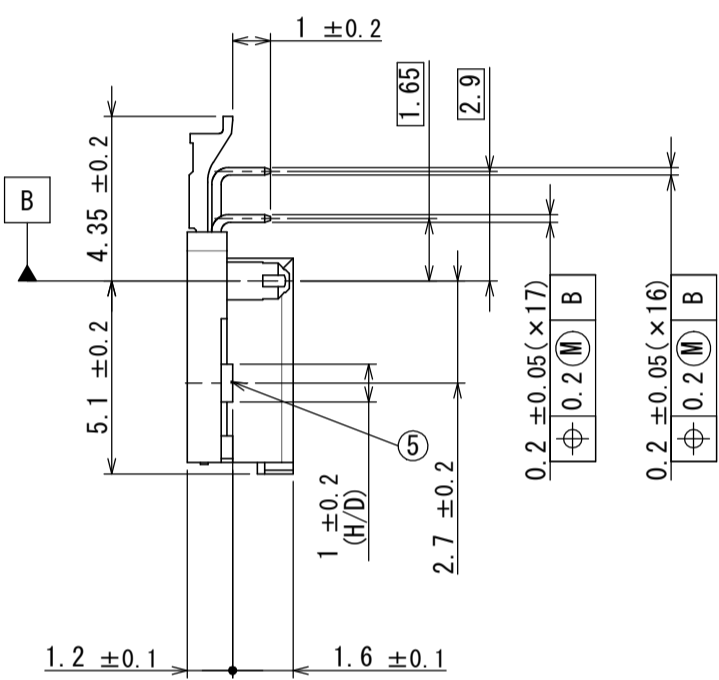
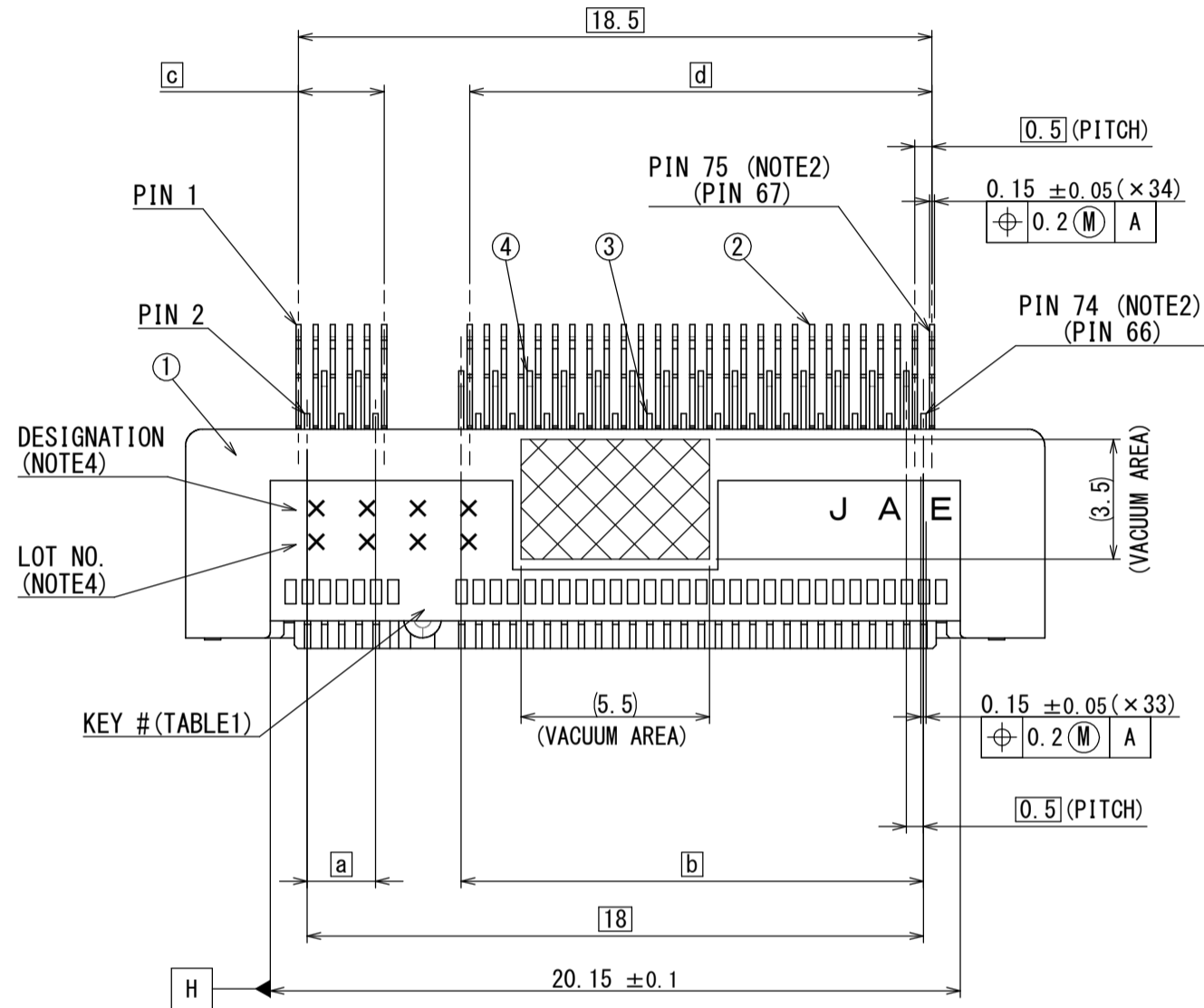
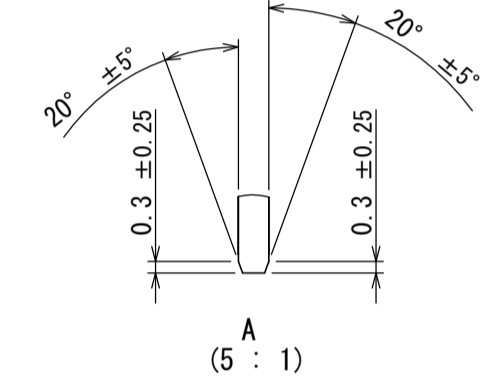
版数 VER.	年月日 DATE	図番 CN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	26/JUN/2014	008839	Specification is changed.		S. YAMAGUCHI	M. SASAKI	T. SHINDOU
3	30/MAR/2015	012835	Correct an error.		S. YAMAGUCHI	M. SASAKI	T. SHINDOU
4	29/JUN/2015	013559	Add KEY version (KEY-M).		S. YAMAGUCHI	M. SASAKI	T. MASUMOTO



APPLICABLE MODULE DIMENSION (REF.) (NOTE2)  
SCALE (2 : 1)



MATING CONDITION  
SCALE (5 : 1)



APPLICABLE P.C.B LAYOUT  
SCALE (2 : 1)

NOTE1. THE COPLANARITY OF CONTACT AND HOLD DOWN SHALL BE 0.1mm MAXIMUM ON THE SURFACE TABLE.  
NOTE2. THIS NUMBER IS PIN-OUT NUMBER DEFINED BY NGFF SPECIFICATION.  
NOTE3. THIS CONNECTOR IS HALOGEN FREE CORRESPONDENCE PRODUCT.  
NOTE4. PRODUCTION LOT No. & MODIFY CODE AS INDICATED.

(Ex. LOT NO.) T 5 Y B  
LOT NUMBER OF CURRENT DAY (SEE TABLE 2)  
MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY, OCT.:0, NOV.:X, DEC.:Y)  
YEAR (LAST DIGIT ONLY)  
MANUFACTURE CODE  
(DESIGNATION) S M 3 B  
KEY POSITION △  
TYPE: B, E, M  
SERIES PREFIX

TABLE 1 △

KEY#	X	a	b	c	d
B	+5.625	2	13.5	2.5	13.5
E	+2.625	5	10.5	5.5	10.5
M	-6.125	14	1.5	14	2

TABLE 2. LOT NUMBER CODE OF CURRENT DAY (END OF LOT No.)

DAY	1	2	3	4	5	6	7	8	9	10	
CODE	1	2	3	4	5	6	7	8	9	0	
DAY	11	12	13	14	15	16	17	18	19	20	
CODE	A	B	C	D	E	F	G	H	J	K	
DAY	21	22	23	24	25	26	27	28	29	30	31
CODE	L	M	N	P	Q	R	S	T	V	W	X

符号 No.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
5	HOLD DOWN	2	COPPER ALLOY	TIN PLATING OVER Ni	
4	LOWER CONTACT2	16	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
3	LOWER CONTACT1	17	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
2	UPPER CONTACT	34	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
1	INSULATOR	1	THERMO PLASTIC		

仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE) 22/JUL/2013	尺度 (SCALE) 5:1	シリーズ (SERIES) SM3	日本航空電子工業株式会社
一般公差 (GENERAL TOLERANCE)	製造 DR.	担当 CHK.	名称 (TITLE) SM3ZS067B120**2		
寸法 (DIMENSION): ±0.8 × ±0.4 ×× ±0.1 ××× ±	製造 APPD.	承認 APPD.	質量 (MASS)		
角度 (ANGLES): ×° ± ××° ±	製造 CHK.	承認 APPD.	図面番号 (DRAWING NO.) SJ114364		
単位 (UNIT): mm	製造 APPD.	承認 APPD.	版数 (VER.) 4		